MSKSEMI 美森科













ESD

TSS

MOV

GDT

PLED

2CL72A-MS/2CL73A-MS

Product specification





Features

- Super small size
- High reliability
- High speed switching

Typical Applications

Mechanical Data

Package: DO-210

Epoxy meets UL 94 V-0 flammability rating

• Terminals: Pure tin plated leads, solderable per

J-STD-002 and JESD22-B102

• Polarity: Color band denotes the cathode end

Reference News

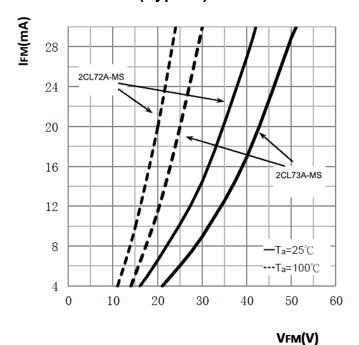
PACKAGE OUTLINE	Pin Configuration	Mark	ing
		T72A	T73A
		2CL72A-MS	2CL73A-MS

Maximum Ratings (Ta=25℃ Unless otherwise specified)

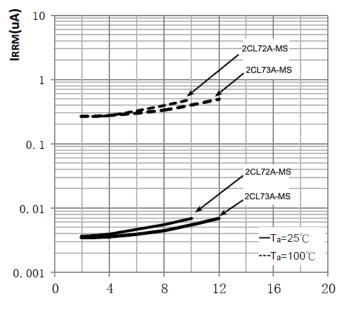
PARAMETER	SYMBOL	UNIT	Conditions	2CL72A-MS	2CL73A-MS
Device marking code				T72A	T73A
Repetitive Peak Reverse Voltage	V _{RRM}	KV		10	12
Non-Repetitive Peak Reverse Voltage	V _{RSM}	KV		12	15
Average Forward Current	I _{F(AV)}	mA	60Hz half-sine wave, Resistance load, Ta=25°C		5
Non-Repetitive Forward Surge Current	I _{FSM}	Α	60Hz half-sine wave,1 cycle, Ta = 25°C	0.5	
Peak Forward Voltage	V _{FM}	V	I _{FM} =10mA	36	45
	Irrm	μА	V _{RM} = V _{RRM} , Ta=25°C		2
Peak Reverse Current			V _{RM} = V _{RRM} , Ta=100°C		5
Reverse Recovery time	t _{rr}	μs	l=2mA,l _{RM} =4mA,l _{RR} =1mA	0	.08
Operating Ambient Temperature	Ta	°C		-40 -	- +100
Storage Temperature	T_{stg}	°C		-40 -	- +120
Virtual Junction Temperature	T _(vj)	°C		120	



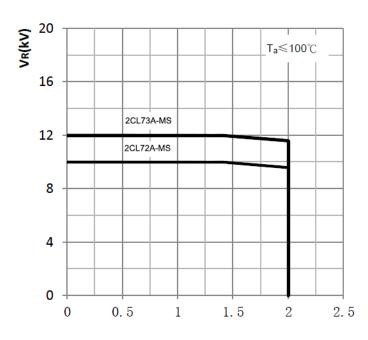
Characteristics (Typical)



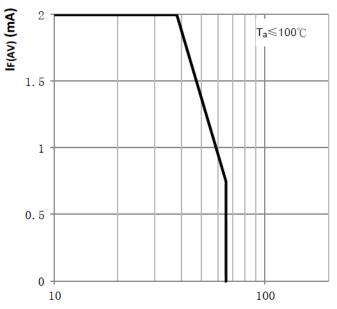




VRM (kV) Figure 2. Reverse characteristics



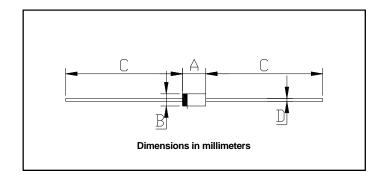
IF(AV) (mA) Figure 3. VR-IF(AV) Curve



fh(kHz) Figure 4. IF(AV)-fh Curve



Outline Dimensions



DO-210					
Dim	Min	Max			
Α	9.8	10.2			
В	2.3	2.7			
С	26	/			
D	0.47	0.53			

Order information

Orderable Device	Package	Packing Option
2CL72A-MS/2CL73A-MS	DO-210	5000PCS



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